

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (currently amended): A multilayer printed wiring board comprising:

a core substrate;

a first conductor layer having a plurality of conductor circuits formed on said core

substrate;

an interlayer insulating layer [[and]] formed over said first [[a]] conductor layer
formed on a and said core substrate, the conductor layer being electrically connected through
a via hole;

a second conductor layer having a plurality of conductor circuits formed on said
interlayer insulating layer; and

a via hole structure electrically connecting one of said conductor circuits of said first
conductor layer and one of said conductor circuits of said second conductor layer,

wherein said first a thickness of the conductor layer on said core substrate has a
thickness which is larger than a thickness of [[the]] said second conductor layer on [[the]]
said interlayer insulating layer.

Claim 2 (currently amended): The [[A]] multilayer printed wiring board comprising:
an interlayer insulating layer and a conductor layer formed on a core substrate, the conductor
layer being electrically connected through a via hole, according to claim 1, wherein said if a
thickness of [[the]] said first conductor layer on said core substrate is $\alpha 1$, said and a thickness
of [[the]] said second conductor layer on [[the]] said interlayer insulating layer is $\alpha 2$, and $\alpha 1$
and $\alpha 2$ satisfy $\alpha 2 < \alpha 1 \leq 40\alpha 2$ $\alpha 2 < \alpha 1 < 40\alpha 2$.

Claim 3 (currently amended): The multilayer printed wiring board according to claim
1, wherein said thickness of said first conductor layer on said core substrate is $\alpha 1$, said

thickness of said second conductor layer on said interlayer insulating layer is $\alpha 2$, and said $\alpha 1$ satisfies $2\alpha 2 \leq \alpha 1 \leq 40\alpha 2$ $2\alpha 2 < \alpha 1 < 40\alpha 2$.

Claim 4 (currently amended): The multilayer printed wiring board according to claim 1, wherein the first conductor layer ~~[[of]]~~ on said core substrate ~~is the conductor layer for~~ comprises a power supply layer or ~~the conductor layer for~~ an earth.

Claim 5 (currently amended): The multilayer printed wiring board according to claim 1, further comprising ~~wherein~~ a capacitor ~~[[is]]~~ mounted on a surface of the multilayer printed wiring board over said second conductor layer.

Claim 6 (currently amended): A multilayer printed wiring board comprising:
a core substrate comprising a multilayer core substrate comprising not less than three layers including at least one inner conductor layer having a plurality of conductor circuits;
a conductor layer having a plurality of conductor circuits formed over said core substrate;

an interlayer insulating layer and a formed over said conductor layer formed on a and said core substrate; and ~~[[,]]~~ the conductor layer being electrically connected through a via hole;

a through hole structure formed through said interlayer insulating layer and electrically connecting one of said conductor circuits of said at least one inner conductor layer and one of said conductor circuits of said conductor layer formed over said core substrate,

wherein said core substrate is a multilayer core substrate comprising not less than three layers including a thick conductor layer as an inner layer; and the conductor layer as the at least one inner conductor layer of said core substrate and the conductor layer on a surface of over said core substrate are the conductor layers for include a power supply layer or the conductor layers for an earth.

Claim 7 (currently amended): ~~The~~ [[A]] multilayer printed wiring board ~~comprising:~~
~~according to claims 6, wherein an interlayer insulating layer and a conductor layer formed on~~
~~a core substrate, the conductor layer being electrically connected through a via hole, wherein~~
~~said core substrate is a multilayer core substrate comprising not less than three layers~~
~~including a thick conductor layer as an inner layer; and a conductor layer as an~~ said at least
one inner conductor layer of said core substrate ~~is the conductor layer as a~~ comprises the
power supply layer or the conductor layer as an earth, and that a said conductor layer is
formed on a surface [[layer]] of said core substrate and comprises a signal line.

Claim 8 (currently amended): A multilayer printed wiring board according to claim 6,
wherein ~~a thickness of the~~ at least one inner conductor layer [[on]] of said core substrate has a
thickness which is larger than a thickness of the conductor layer ~~on the interlayer insulating~~
layer formed over the surface of said core substrate.

Claim 9 (currently amended): The multilayer printed wiring board according to claim
6, wherein the at least one inner conductor layer as the inner layer of said core substrate [[is]]
comprises not less than two inner conductor layers.

Claim 10 (currently amended): The multilayer printed wiring board according to
claim 6, wherein said core substrate ~~is constituted so that the conductor layer as said inner~~
~~layer is formed on each surface of~~ comprises an electrically isolated metallic plate, ~~through a~~
~~resin layer and a plurality of insulating layers formed on surfaces of said electrically isolated~~
~~metallic plate, respectively, and so that said conductor layer on the surface layer is formed~~
~~outside of the conductor layer as the inner layer through the resin layer~~ said at least one inner
conductor layer of said core substrate comprises a plurality of inner conductor layers, and the
inner conductor layers are formed on the insulating layers, respectively.

Claim 11 (currently amended): The multilayer printed wiring board according to
claim 6, wherein the conductor layer is formed on a surface of said core substrate, and said at

~~least one inner layer of said core substrate comprises a thick conductor layer as the inner layer and a thin conductor layer as~~ has a thickness which is larger than a thickness of the conductor layer on the surface layer formed on the surface of said core substrate.

Claim 12 (currently amended): The multilayer printed wiring board according to claim 2, wherein the first conductor layer ~~[[of]]~~ formed on said core substrate ~~is the conductor layer for~~ comprises a power supply layer or ~~the conductor layer for~~ an earth.

Claim 13 (currently amended): The multilayer printed wiring board according to claim 2, further comprising ~~wherein~~ a capacitor ~~[[is]]~~ mounted ~~[[on]]~~ over a surface of the ~~multilayer printed wiring board~~ said core substrate.

Claim 14 (currently amended): A multilayer printed wiring board according to claim 7, wherein said at least one inner layer ~~a thickness of the conductor layer on~~ of said core substrate has a thickness which is larger than a thickness of the conductor layer ~~on the interlayer insulating layer~~ formed on said core substrate.

Claim 15 (currently amended): The multilayer printed wiring board according to claim 7, wherein said at least one inner conductor layer ~~the conductor layer as the inner layer~~ of said core substrate ~~[[is]]~~ comprises not less than two inner conductor layers.

Claim 16 (currently amended): The multilayer printed wiring board according to claim 7, wherein said core substrate ~~is constituted so that the conductor layer as said inner layer is formed on each surface of~~ comprises an electrically isolated metallic plate ~~through a resin layer and a plurality of insulating layers formed on surfaces of said electrically isolated metallic plate, respectively, so that said conductor layer on the surface layer is formed outside of the conductor layer as the inner layer through the resin layer~~ said at least one inner conductor layer of said core substrate comprises a plurality of inner conductor layers, and the inner conductor layers are formed on the insulating layers, respectively.

Claim 17 (currently amended): The multilayer printed wiring board according to claim [[7]] 6, further comprising a second conductor layer having a plurality of conductor circuits formed over said interlayer insulating layer, wherein said conductor layer is formed on a surface of said core substrate, said at least one inner layer of said core substrate comprises a thick conductor layer as the inner layer and a thin conductor layer as has a thickness which is larger than a thickness of the conductor layer on the surface layer formed on the surface of said core substrate, and the thickness of said conductor layer formed on the surface of said core substrate is larger than a thickness of said second conductor layer.

Claim 18 (new): A multilayer printed wiring board comprising:
a core substrate; and
a multilayered structure formed on said core substrate and including a first conductor layer having a plurality of conductor circuits formed on said core substrate, at least one interlayer insulating layer formed over said first conductor layer, and a second conductor layer having a plurality of conductor circuits formed on said at least one interlayer insulating layer,
wherein said first conductor layer on said core substrate has a thickness which is larger than a thickness of said second conductor layer on said at least one interlayer insulating layer.

Claim 19 (new): The multilayer printed wiring board according to claim 18, wherein said thickness of said first conductor layer on said core substrate is $\alpha 1$, said thickness of said second conductor layer on said interlayer insulating layer is $\alpha 2$, and $\alpha 1$ and $\alpha 2$ satisfy $\alpha 2 < \alpha 1 < 40\alpha 2$.

Claim 20 (new): The multilayer printed wiring board according to claim 18, wherein said thickness of said first conductor layer on said core substrate is $\alpha 1$, said thickness of said

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second conductor layer on said interlayer insulating layer is α_2 , and said α_1 satisfies $2\alpha_2 < \alpha_1$
 $< 40\alpha_2$.